

IN THE CLAIMS

Presented below is a complete list of claims with changes marked up:

1. (Currently Amended) A package comprising:

a substrate having a plurality of traces in one area on a surface of the substrate, each of the plurality of traces having first and second ends, the first ends of the plurality of traces located at a first side of the area of the substrate and second ends of the plurality of traces located at a second side of the area opposite the first side;

a plurality of wires coupling the plurality of traces to form a coil to electrically isolate at least two circuit components, the coil being formed by having each of the plurality of wires coupling a first end of one trace of the plurality of traces to a second end of another of the plurality of traces located adjacent to the one trace; and

a resistor, on the surface of the substrate, coupled to the coil.

2. (Original) The package of claim 1 wherein the plurality of traces are substantially parallel to each other.

3. (Canceled)

4. (Original) The package of claim 1 wherein the traces are welded to the wires.

5. (Original) The package of claim 1 wherein the traces have a length of 2 mm and a pitch of 1 mm.

6. – 15. (Canceled)

16. (Previously Presented) A package comprising:

a substrate;

a coil to electrically isolate at least two circuit components, the coil including a plurality of traces on a surface of the substrate and a plurality of wire bonds, each wire bond coupling one trace to another trace, wherein a magnetic field is created when current flows through the coil; and

a resistor, on the surface of the substrate, coupled to the coil.

17. (Currently Amended) A package comprising:

a substrate;

a plurality of traces on a surface of the substrate;

a plurality of wires, each wire coupling a first trace of the plurality of traces to a second trace of the plurality of traces to form a coil to electrically isolate at least two circuit components; and

a resistor, on the surface of the substrate, coupled to the coil.

18. (Previously Presented) The package of claim 1, wherein the traces are wire-bonded to the wires.